

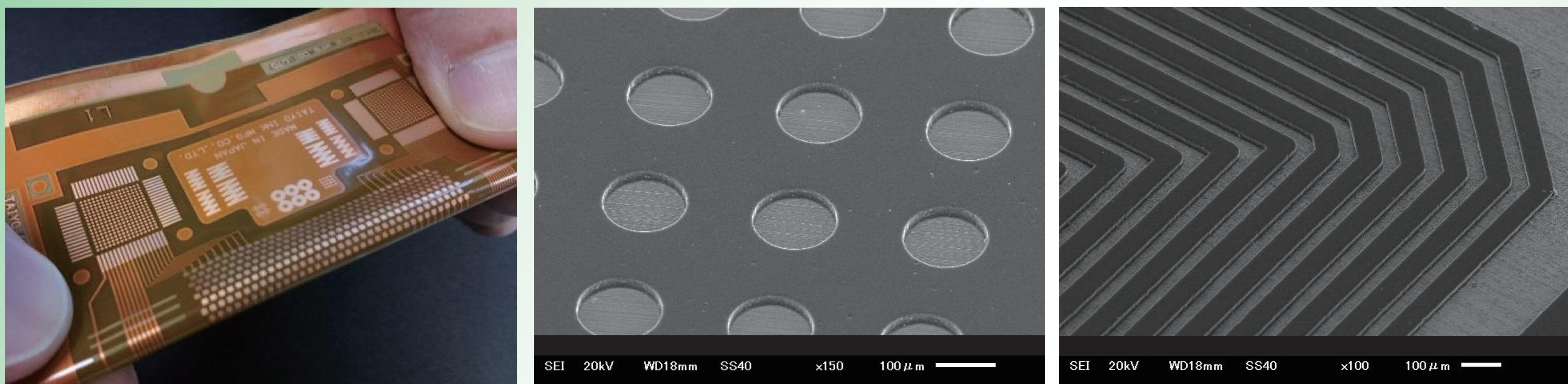


# 感光性カバーレイフィルム

## Photo Imageable Cover Lay Film

### 特長 Features

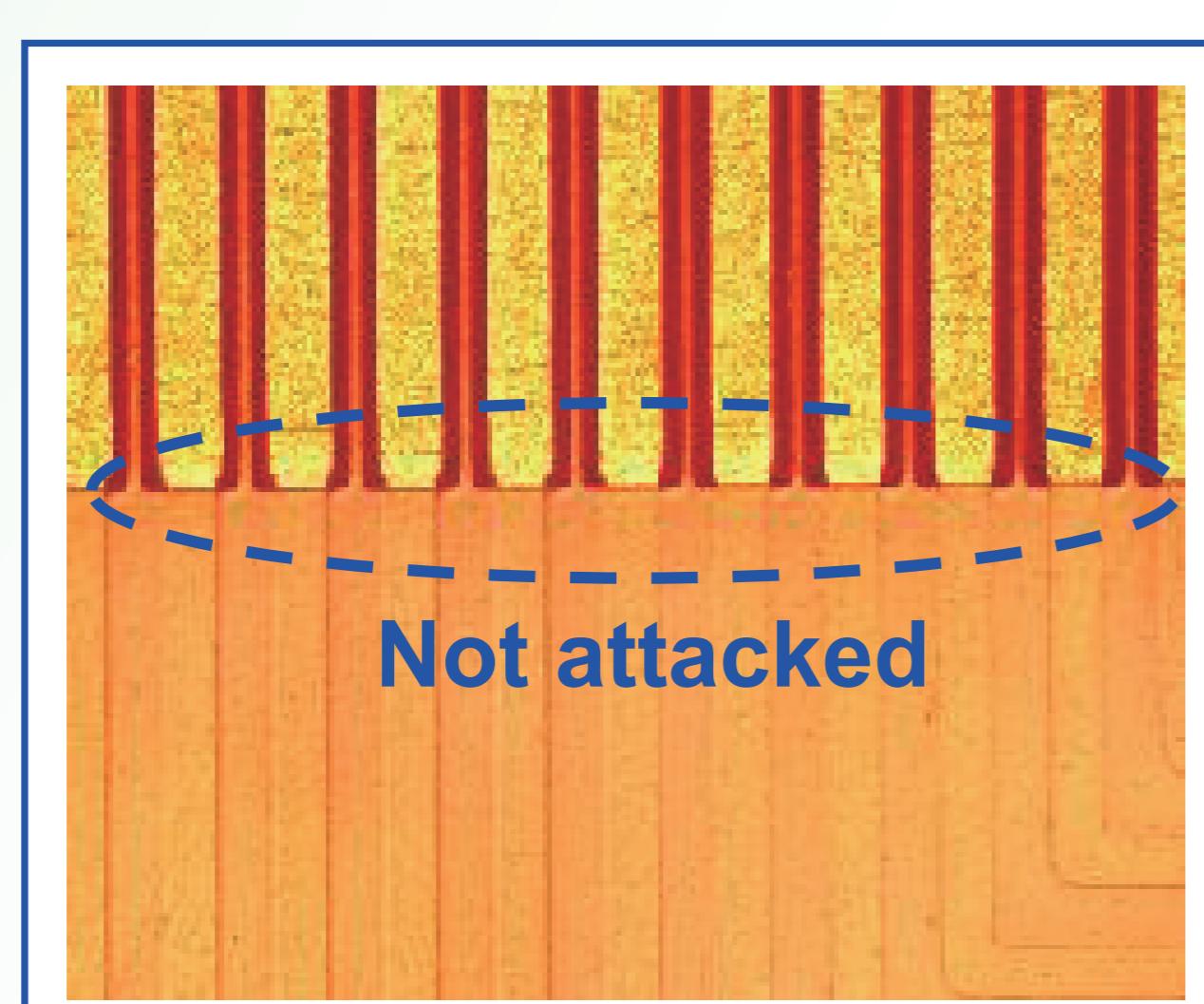
- 高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム  
Photo imageable polyimide film with coexistence of high resolution and high bendability
- 現行のプリント配線板製造ラインへの適用を実現  
Applicable to current PWB photolithography process
- 優れた耐熱性と絶縁信頼性と難燃性(VTM-0相当)を実現  
Excellent heat resistance, insulation reliability and flame resistance (VTM-0 equivalent)



### 特性 Properties

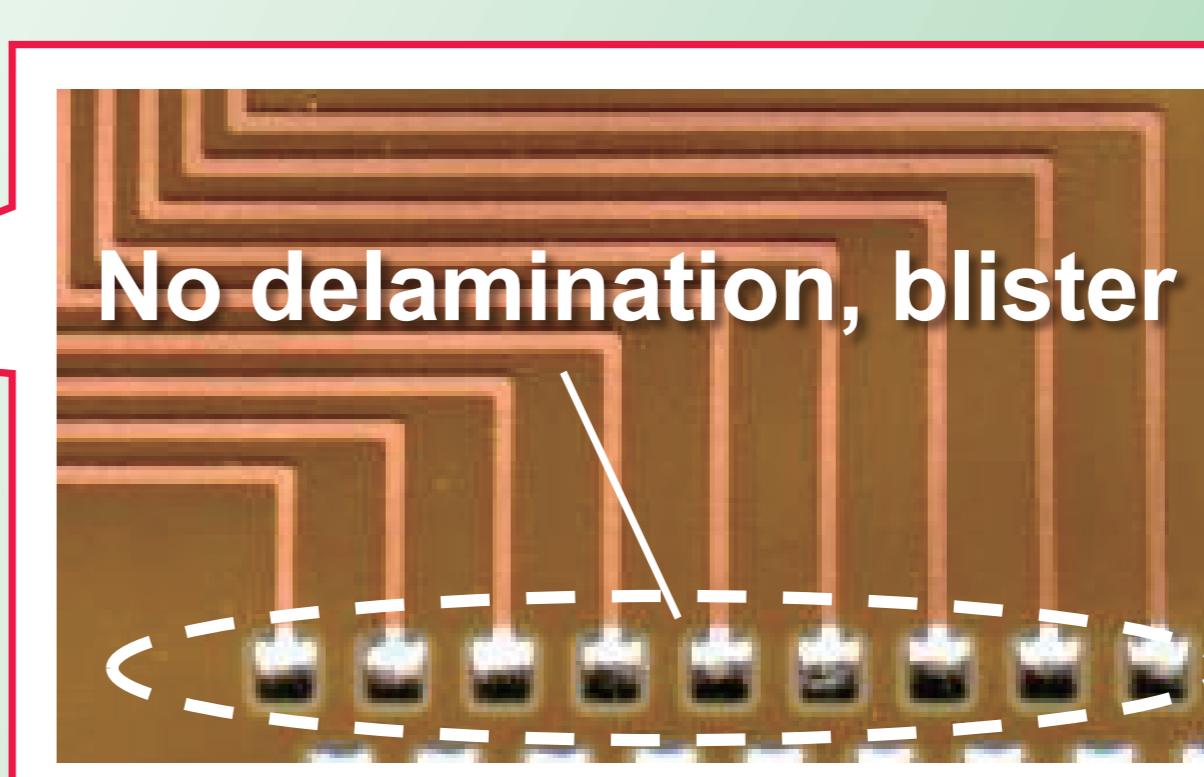
Item	Condition	Result
Pencil hardness	JIS 5600	4H
Acid resistance	10 vol% H <sub>2</sub> SO <sub>4</sub> aq. 25 deg.C × 20 min	Pass
Alkaline resistance	10 wt% NaOHaq. 25 deg.C × 20 min	Pass
Heat resistance	Solder floating 288 deg.C × 10 sec	Pass
Au plating resistance	ENIG Ni:4 um Au:0.1um	Pass
Tg	TMA	167 deg.C
Bendability	180 deg. folding	above 20 times

#### ENIG resistance 【Ni:4.0um Au:0.1um】



#### Solder heat resistance

【288deg.C × 10sec × 2 times】



ZXCV